





Impedance & Stackup Report

Single Ended								
Index	Layer	Imp Model	WithCoat	Ref Layer	Orginal LW/LS(mil)	Adjusted LW/LS(mil)	Adjusted Imp(ohm)	Org Imp (ohm)
1	L1		Y	L2	ORG_LW: 6.000	ADJ_LW: 5.100	49.35	50.0+/-10%
2	L3		N	L4/L2	ORG_LW: 4.000	ADJ_LW: 3.856	49.16	50.0+/-10%
3	L6		N	L5/L7	ORG_LW: 4.000	ADJ_LW: 3.895	49.17	50.0+/-10%
4	L8		Y	L7	ORG_LW: 6.000	ADJ_LW: 5.100	49.44	50.0+/-10%
Differential								
Index	Layer	Imp Model	WithCoat	Ref Layer	Orginal LW/LS(mil)	Adjusted LW/LS(mil)	Adjusted Imp(ohm)	Org Imp (ohm)
5	L1		Y	L2	ORG_LW: 5.100 ORG_S:11.000	ADJ_LW: 4.900 ADJ_S:11.200	100.36	100.0+/-10%
6	L1		Y	L2	ORG_LW: 4.000 ORG_S: 6.500	ADJ_LW: 4.000 ADJ_S: 6.500	100.06	100.0+/-10%
7	L3		N	L4/L2	ORG_LW: 3.500 ORG_S:10.000	ADJ_LW: 3.850 ADJ_S: 9.650	100.57	100.0+/-10%
8	L6		N	L5/L7	ORG_LW: 3.500 ORG_S:10.000	ADJ_LW: 3.820 ADJ_S: 9.680	101.31	100.0+/-10%
9	L8		Y	L7	ORG_LW: 4.000 ORG_S: 6.500	ADJ_LW: 4.000 ADJ_S: 6.500	100.17	100.0+/-10%
10	L8		Y	L7	ORG_LW: 5.100 ORG_S:11.000	ADJ_LW: 4.900 ADJ_S:11.200	100.51	100.0+/-10%
Index	Layer	Imp Model	WithCoat	Ref Layer	Orginal LW/LS(mil)	Adjusted LW/LS(mil)	Adjusted Imp(ohm)	Org Imp (ohm)
11	L1		Y	L3	ORG_LW:17.500 ORG_D:12.000	ADJ_LW:15.000 ADJ_D:13.250	49.46	50.0+/-10%

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叠板图:

Lyr	残铜率_铜重	Image	Er	芯板结构	客户要求(mil)	物料名称(mil)
gtl	CU(%):79 0.33OZ		0.00			三井 Foil 0.33oz
			4.00		3.58+0.71/-0.71mil	2113 RC58
12s	CU(%):87 10Z		4.29	2116*1	5.12+0.98/-0.98mil[101]	5.12mil 1/1(不含铜)
13s	CU(%):81 10Z		4.02		4.8+0.98/-0.98mil	2116H RC58
14s	CU(%):81 10Z		4.27	7628*4+1080*1	32.68+3.94/-3.94mil[102]	32.68mil 1/1(不含铜)
15s	CU(%):89 10Z		4.02		4.8+0.98/-0.98mil	2116H RC58
16s	CU(%):80 10Z		4.29	2116*1	5+0.98/-0.98mil[103]	5.12mil 1/1(不含铜)
17s	CU(%):88 10Z		4.00		3.58+0.71/-0.71mil	2113 RC58
gbl	CU(%):77 0.33OZ		0.00			三井 Foil 0.33oz

Finish Board Thickness(mil): 73.62+ 7.36/- 7.36